80386DX
32-Bit Microprocessor

Logic Diagram

FEATURES:

- 32-Bit microprocessor
- RAD-PAK® radiation-hardened against natural space radiation
- Total dose hardness:
  - >100 Krad (Si), dependent upon space mission
- Single event effect:
  - SEL_{TH} = 37-60 MeV/mg/cm^2
  - SEU_{TH} = 3.4 MeV/mg/cm^2
  - SEU Cross section 1E-3 cm^2/bit
- Package:
  - 164 Pin RAD-PAK® quad flat pack
- 8, 16, 32-Bit data types
- 8 general purpose 32-Bit registers
- Hardware debugging support
- Very large address space:
  - 4 gigabyte physical
  - 64 terabyte Virtual
  - 4 gigabyte maximum segment size
- Integrated memory management unit
  - Virtual memory support
  - Four levels of protection
  - Fully compatible with 80C286
- Optimized for system development
  - Pipelined instructions
  - On-chip caches support address translation
  - 32 megabytes/sec bus bandwidth

DESCRIPTION:

Maxwell Technologies′ 80386DX high performance 32-bit microprocessor features a geater than 100 krad (Si) total dose tolerance, dependent upon space mission. It is designed for very high performance and multitasking operating systems. The integrated memory management and protection architecture includes address translation registers, multitasking hardware and a protection mechanism to support operating systems. The 80386DX allows simultaneous running of multiple operations. In addition, the 80386DX is capable of execution at sustained rates of between 3 and 4 million instructions per second. It offers new testability and debugging features, including a self-test and direct access to the page translation cache.

Maxwell Technologies' patented RAD-PAK® packaging technology incorporates radiation shielding in the microcircuit package. It eliminates the need for box shielding while providing the required radiation shielding for a lifetime in orbit or space mission. In a GEO orbit, RAD-PAK provides greater than 100 krad (Si) radiation dose tolerance. This product is available with screening up to Class S.

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TABLE 1. 80386DX PIN DESCRIPTION

PIN	SYMBOL	DESCRIPTION
1-7, 9, 10, 12, 13, 16, 17, 20, 21, 24, 146-149, 152-154, 156-159, 161-163	A16-A11, A9, A10, A7, A8, A5, A6, A3, A4, A2, A31-A28, A27-A25, A23-A22, A20-A18	Address Bus
8, 18, 19, 22, 23, 25, 28-30, 33, 36, 38-40, 47, 48, 65, 66, 68, 73, 76, 77, 82, 84, 86, 88, 103, 106, 107, 114, 125, 126, 129, 130,133, 134, 145, 155, 160, 164	NC	Not Connected
11, 15, 27, 32, 35, 43, 51, 53, 55, 57, 61, 70, 92, 95, 100, 111, 118, 122, 138, 142, 151	V_{SS}	Ground
14, 26, 31, 34, 44, 50, 52, 54, 56, 58, 62, 69, 91, 96, 99, 110, 117, 137, 141, 150,	V_{CC}	Power Supply
37	INTR	Interupt Request
41	NMI	Non-Maskable Interupt Request
42	PEREQ	Processor Extension Request
45	$\overline{ERROR}$	Error Status
46	RESET	Reset
49	$\overline{BUSY}$	Busy Status
59	$\overline{LOCK}$	Bus Lock
60	W/$\overline{R}$	Write/ Read
63	M/$\overline{IO}$	Memory I/O
64	D/$\overline{C}$	Data Control
67, 71, 72, 74	$\overline{BE2}$, $\overline{BE0}$, $\overline{BE3}$, $\overline{BE1}$	Byte Enables
78	$\overline{BS16}$	Bus Size 16
75	$\overline{NA}$	Next Address
79	HOLD	Bus Hold Request
80	CLK2	CPU Clock 2
81	$\overline{ADS}$	Address Staus
83	$\overline{READY}$	Bus Ready Input
85, 87, 89, 90, 93, 94, 97, 98, 102, 104, 105, 108, 109, 112, 113, 115, 116, 119, 120, 121, 123, 124, 127, 128, 131, 132, 135, 136, 139, 140, 143, 144,	D1, D2, D4, D0, D6, D3, D8, D5, D7, D10, D9, D12, D11, D14, D13, D15, D16, D18, D17, D20, D22, D19, D24, D21, D25,D23, D27, D26, D29, D28, D31, D30,	Data Bus
101	HLDA	Bus Hold Acknowledge

TABLE 2. 80386DX ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	MIN	MAX	UNIT
Supply Voltage with Respect to Ground	V_{SS}	-0.5	6.5	V
Voltage on other pins		-0.5	V_{CC} +0.5	V
Thermal Impedance	Θ_{JC}	--	1.79	°C/W
Operating Temperature Range (Ambient)	T_A	-55	125	°C
Storage Temperature Range (Ambient)	T_S	-65	150	°C

TABLE 3. DELTA LIMITS

PARAMETER	VARIATION
I_{CC}	±10% of specified value in Table 4
I_{LI}	±10% of specified value in Table 4
I_{LO}	±10% of specified value in Table 4

TABLE 4. 80386DX RECOMMENDED OPERATING CONDITIONS

PARAMETER	SYMBOL	MIN	MAX	UNIT
Digital Supply Voltage	V_{CC}	4.75	5.25	V
Input Low Voltage	V_{IL}	--	0.8	V
Input High Voltage	V_{IH}	2.0	--	V
CLK2 Input Low Voltage	V_{ILC}	--	0.8	V
CLK2 Input High Voltage	V_{IHC}	V_{CC} - 0.8	--	V
Operating Temperature Range	T_A	-55	+125	°C

TABLE 5. 80386DX DC ELECTRICAL CHARACTERISTICS
(V_{CC} = +5V ±5%; T_A = -55°C TO +125°C, UNLESS OTHERWISE SPECIFIED)

PARAMETER	SYMBOL	CONDITION	MIN	MAX	UNIT
Input Leakage Current	I_{LI}	All pins except $\overline{BS16}$, $\overline{PEREQ}$, $\overline{BUSY}$, and $\overline{ERROR}$ $0V \leq V_{IN} \leq V_{CC}$	-15	+15	µA
Output Leakage Current	I_{LO}	$0.45V \leq V_{OUT} \leq V_{CC}$	-15	+15	µA
Output Low Voltage	V_{OL}	I_{OL} = 4 mA: A2 - A31, D0 - D31	--	0.45	V
		I_{OL} = 5 mA: $\overline{BE0}$ - $\overline{BE3}$, W/$\overline{R}$, D/$\overline{C}$, M/$\overline{IO}$, $\overline{LOCK}$, $\overline{ADS}$, HLDA	--	0.45	
Output High Voltage	V_{OH}	I_{OH} = 1 mA: A2 - A31, D0 - D31	2.4	--	V
		I_{OH} = 0.9 mA: $\overline{BE0}$ - $\overline{BE3}$, W/$\overline{R}$, D/$\overline{C}$, M/$\overline{IO}$, $\overline{LOCK}$, $\overline{ADS}$, HLDA	2.4	--	

TABLE 5. 80386DX DC ELECTRICAL CHARACTERISTICS

(V_{CC} = +5V ±5%; T_A = -55°C TO +125°C, UNLESS OTHERWISE SPECIFIED)

PARAMETER	SYMBOL	CONDITION	MIN	MAX	UNIT
Power Supply Current	I_{CC}	CLK2 = 32 MHz with 16 MHz Processor	--	460	mA
		CLK2 = 32 MHz with 20 MHz Processor	--	550	
		CLK2 = 32 MHz with 25 MHz Processor	--	680	
Input Leakage Current	I_{IH}	PEREQ Pin[1]	--	200	µA
	I_{IL}	BS16, BUSY, ERROR Pins[2]	--	-400	µA
CLK2 Capacitance[3]	C_{CLK}	F_C = 1 MHz	--	20	pF
Input or I/O Capacitance[1]	C_{IN}	F_C = 1 MHz	--	20	pF
Output Capacitance[1]	C_{OUT}	F_C = 1 MHz	--	25	pF

1. V_{IH} = 2.4V. PEREQ input has an internal pulldown resistor.

2. V_{IL} = 0.45V. BS16, BUSY and ERROR inputs have an internal pulldown resistor.

3. Guaranteed by design.

TABLE 6. 80386DX AC ELECTRICAL CHARACTERISTICS

(V_{CC} = +5V ±10%; V_{PP} = V_{SS}; T_A = -55°C TO +125°C, UNLESS OTHERWISE SPECIFIED)

PARAMETER	SYMBOL	CONDITION	MIN	MAX	UNIT
Operating Frequency -16 -20 -25	--	Half of CLK2 Frequency	 4 4 4	 16 20 25	MHz
CLK2 Period -16 -20 -25	t_1		 31 25 20	 125 125 125	ns
CLK2 High Time -16 -20 -25	t_{2a}	at 2V	 9 8 7	 -- -- --	ns
CLK2 High Time[1] -16 -20 -25	t_{2b}	at (V_{CC} - 0.8V)	 5 5 4	 -- -- --	ns
CLK2 Low Time -16 -20 -25	t_{3a}	at 2V	 9 8 7	 -- -- --	ns
CLK2 Low Time[1] -16 -20 -25	t_{3b}	at (V_{CC} - 0.8V)	 7 6 5	 -- -- --	ns

TABLE 6. 80386DX AC ELECTRICAL CHARACTERISTICS

(V_{CC} = +5V ±10%; V_{PP} = V_{SS}; T_A = -55°C TO +125°C, UNLESS OTHERWISE SPECIFIED)

PARAMETER	SYMBOL	CONDITION	MIN	MAX	UNIT
CLK2 Fall Time[1] -16 -20 -25	t_4	(V_{CC} - 0.8V) to 0.8V -- -- --	 8 8 7	ns
CLK2 Rise Time[1] -16 -20 -25	t_5	0.8V to (V_{CC} - 0.8V) -- -- --	 8 8 7	ns
A2 - A31 Valid Delay -16 -20 -25	t_6	C_L = 120pF (C_L = 50pF for 25 MHz) 4 4 4	 36 30 21	ns
A2 - A31 Float Delay[1, 2] -16 -20 -25	t_7	 4 4 4	 40 32 30	ns
BE0 - BE3, LOCK Valid Delay -16 -20 -25	t_8	C_L = 75pF (C_L = 50pF for 25 MHz) 4 4 4	 36 30 24	ns
BE0 - BE3, LOCK Float Delay[1, 2] -16 -20 -25	t_9	 4 4 4	 40 32 30	ns
W/R, M/IO, D/C and ADS Valid Delay -16 -20 -25	t_{10}	C_L = 75pF (C_L = 50pF for 25 MHz) 6 6 4	 33 28 21	ns
W/R, M/IO, D/C and ADS Float Delay[1, 2] -16 -20 -25	t_{11}	 6 6 4	 35 30 30	ns
D0 - D31 Valid Delay -16 -20 -25	t_{12}	C_L = 120pF (C_L = 50pF for 25 MHz) 4 4 7	 48 38 27	ns
D0 - D31 Float Delay[1, 2] -16 -20 -25	t_{13}	 4 4 4	 35 27 22	ns
HLDA Valid Delay -16 -20 -25	t_{14}	C_L = 75pF (C_L = 50pF for 25 MHz) 6 6 4	 323 28 22	ns

TABLE 6. 80386DX AC ELECTRICAL CHARACTERISTICS

(V_{CC} = +5V ±10%; V_{PP} = V_{SS}; T_A = -55°C TO +125°C, UNLESS OTHERWISE SPECIFIED)

PARAMETER	SYMBOL	CONDITION	MIN	MAX	UNIT
N̄/Ā Setup Time -16 -20 -25	t_{15}		 11 9 7	 -- -- --	ns
N̄/Ā Hold Time -16 -20 -25	t_{16}		 14 14 3	 -- -- --	ns
B̄S̄1̄6̄ Setup Time -16 -20 -25	t_{17}		 13 13 7	 -- -- --	ns
B̄S̄1̄6̄ Hold Time -16 -20 -25	t_{18}		 21 21 3	 -- -- --	ns
R̄Ē̄ĀDȲ Setup Time -16 -20 -25	t_{19}		 21 12 9	 -- -- --	ns
R̄Ē̄ĀDȲ Hold Time -16 -20 -25	t_{20}		 4 4 4	 -- -- --	ns
D0 - D31 Read Setup Delay -16 -20 -25	t_{21}		 11 11 6	 -- -- --	ns
D0 - D31 Read Hold Delay -16 -20 -25	t_{22}		 6 6 5	 -- -- --	ns
HOLD Setup Time -16 -20 -25	t_{23}		 26 17 15	 -- -- --	ns
HOLD Hold Time -16 -20 -25	t_{24}		 5 5 3	 -- -- --	ns
RESET Setup Time -16 -20 -25	t_{25}		 10 10 10	 -- -- --	ns

TABLE 6. 80386DX AC ELECTRICAL CHARACTERISTICS

(V_{CC} = +5V ±10%; V_{PP} = V_{SS}; T_A = -55°C TO +125°C, UNLESS OTHERWISE SPECIFIED)

PARAMETER	SYMBOL	CONDITION	MIN	MAX	UNIT
RESET Hold Time -16 -20 -25	t_{26}		 4 4 3	 -- -- --	ns
NMI, INTR Setup Time[3] -16 -20 -25	t_{27}		 16 16 6	 -- -- --	ns
NMI, INTR Hold Time[3] -16 -20 -25	t_{28}		 16 16 6	 -- -- --	ns
REREQ, ERROR, BUSY Setup Time[3] -16 -20 -25	t_{29}		 16 14 6	 -- -- --	ns
REREQ, ERROR, BUSY Hold Time[3] -16 -20 -25	t_{30}		 5 5 5	 -- -- --	ns

1. Guaranteed by design.

2. Float condition occurs when maximum when output current becomes less than ILO in magnitude.

3. These inputs are allowed to be asynchronous to CLK2. The setup and hold specifications are given for testing purposes, to assure recognition within a specific CLK2 period.

FIGURE 1. AC TEST LOADS

C_L = 120 pF on A2–A31, D0–D31
C_L = 75 pF on BE0#–BE3#, W/R#, M/IO#, D/C#, ADS#,
LOCK#, HLDA
C_L includes all parasitic capacitances.

FIGURE 2. CLK2 TIMING

FIGURE 3. INPUT SETUP AND HOLD TIME

FIGURE 4. OUTPUT VALID DELAY TIMING
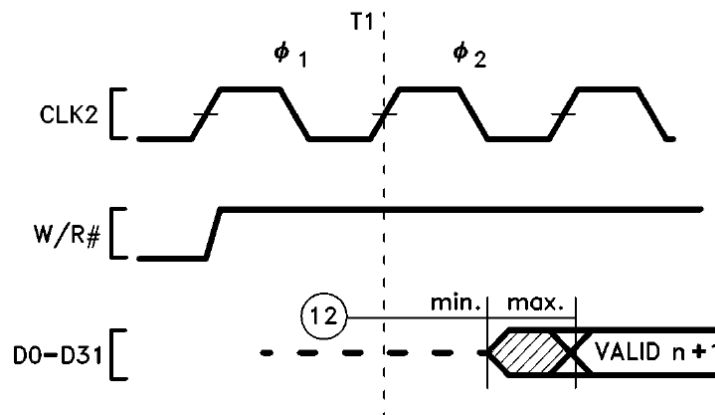

FIGURE 5. WRITE DATA VALID DELAY TIMING (25 MHz)

FIGURE 6. WRITE DATA HOLD TIMING (25 MHz)

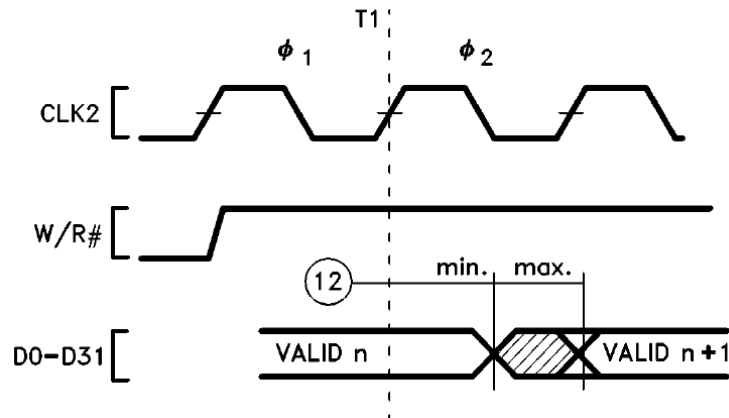FIGURE 7. WRITE DATA VALID DELAY TIMING (20 MHz)

FIGURE 8. TYPICAL OUTPUT VALID DELAY VERSUS LOAD CAPACITANCE AT MAXIMUM OPERATING TEMPERATURE (C_L = 120 pF)
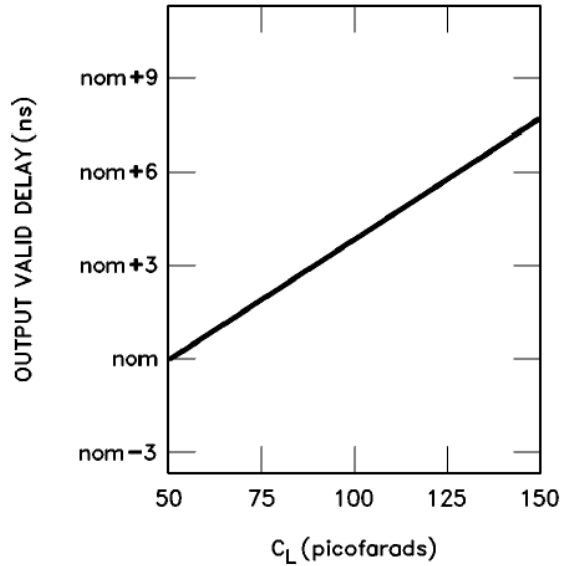

NOTE:
This graph will not be linear outside of the C_L range shown.

FIGURE 9. TYPICAL OUTPUT VALID DELAY VERSUS LOAD CAPACITANCE AT MAXIMUM OPERATING TEMPERATURE (C_L = 75 pF)
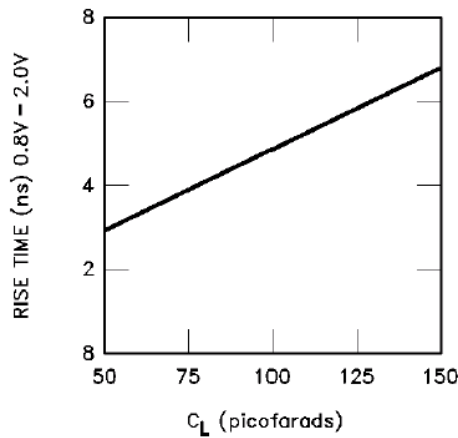

NOTE:
This graph will not be linear outside of the C_L range shown.

FIGURE 10. TYPICAL OUTPUT VALID DELAY VERSUS LOAD CAPACITANCE AT MAXIMUM OPERATING TEMPERATURE (C_L = 50 PF)

NOTE:
This graph will not be linear outside of the C_L range shown.

FIGURE 11. TYPICAL OUTPUT RISE TIME VERSUS LOAD CAPACITANCE AT MAXIMUM OPERATING TEMPERATURE

NOTE:
This graph will not be linear outside of the C_L range shown.

FIGURE 12. Output Float Delay and HLDA and Delay Timing

FIGURE 13. Reset Setup and Hold Timing, and Internal Phase

The second internal processor phase following RESET high-to-low transition (provided t_{25} and t_{26} are met) is $\phi2$.

164-Pin Rad-Pak® Quad Flat Package

Symbol	Dimension		
	Min	Nom	Max
A	0.118	0.132	0.146
b	0.007	0.008	0.013
c	0.004	0.006	0.009
D	1.138	1.150	1.167
D1	1.000 BSC		
e	0.025 BSC		
S1	0.013	0.071	--
F1	0.890	0.895	0.900
F4	0.880	0.890	0.899
L	2.500	2.520	2.540
L1	2.485	2.500	2.505
L2	1.690	1.700	1.710
A1	0.078	0.090	0.102
N	164		

Q164-01
Note: All dimensions in inches

Important Notice:

These data sheets are created using the chip manufacturer's published specifications. Maxwell Technologies verifies functionality by testing key parameters either by 100% testing, sample testing or characterization.

The specifications presented within these data sheets represent the latest and most accurate information available to date. However, these specifications are subject to change without notice and Maxwell Technologies assumes no responsibility for the use of this information.

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Product Ordering Options

Model Number

| 80386DX | RP | Q | X | XX |

| | | | Feature | Option Details |

Processing Speed in MHz
16
20
25

Screening Flow

Monolithic
S = Maxwell Class S
B = Maxwell Class B
E = Engineering (testing @ +25°C)
I = Industrial (testing @ -55°C,
+25°C, +125°C)

Package

Q = Quad Flat Pack

Radiation Feature

RP = RAD-PAK® package

Base Product
Nomenclature

32-Bit Microprocessor